



Model FAB1

DIE BONDER PLATFORM



fab1 is an automatic assembly system for handling virtually any kind and size of component, as well as for applying adhesives. Typical applications are pick & place-, sorting-, inspection- and test function. Flexibility, easy operation and optional configurations of this compact equipment permit the fabrication of standard and advanced packaging technologies like chip on board, multichip modules, chip on chip, flip chip, eutectic soldering processes etc. fab1 uses the latest hardware technology combined with a network transparent fully graphical control software interacting with a SQL server backend.



Model FAB1

Key features

- 500mm x 430mm area of operations for the xy axis
- component presentation in all common forms,
 - Waffle Pack & GEL PAK
 - 1 Wafer up to 12
 - 2 Wafer up to 8" parallel presented
 - Tape Feeder
- Linux based open software architecture with SQL storage backend and various options
- basic system with iron core linear motors and modular hardware configuration such as automatic dispenser change
- flexible system design to integrate customer specific requirements
- Integrated Flow Box with separation efficiency of 99,995%

Hardware Basic

- Rugged compact steel mainframe with an embedded vibration damped aluminum casting
- Iron core linear motors for xy axis integrated in the aluminum casting.
- PC System with dual core processor
- Integrated flow box with H14 filter

Software Basic

- Open software architecture with SQL backend
- GUI, graphical user interface supported with expert panels
- Linux-2.6 operating system
- Image recognition feature based with pattern matcher, circle-, edge- and ink dot matching
- easy to operate and program

Options

- toolbox
- eject system
- dispenser
- stamping unit
- flip chip unit
- up looking camera
- tape feeder
- eutectic unit

Options

- Wafer mapping
- Offline Programming, CAD data import
- Inspection
- Manual Mode
- Traceability